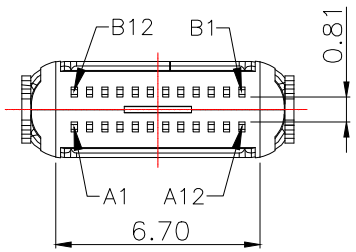
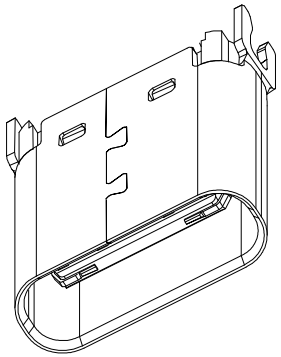
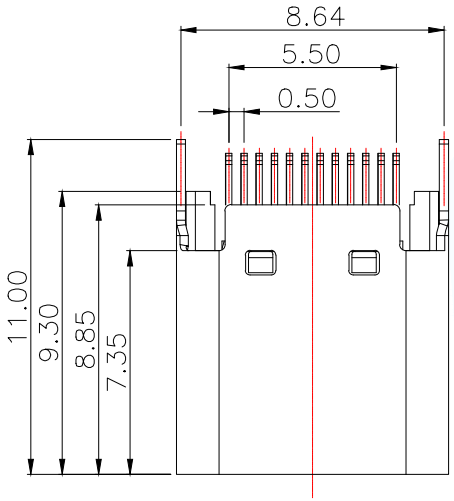
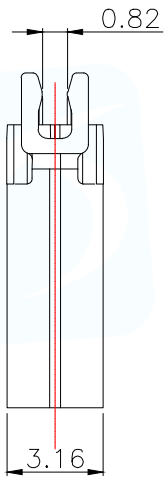
ROHS Compliant

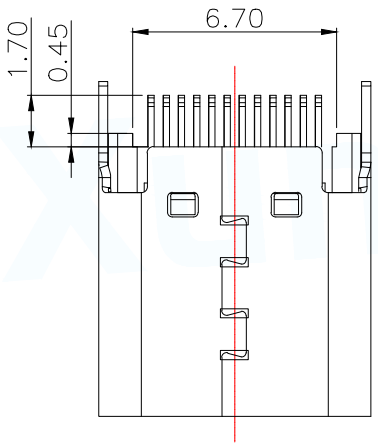
MAPX	MODIFICATION	DATE	DRAW	APPROVE

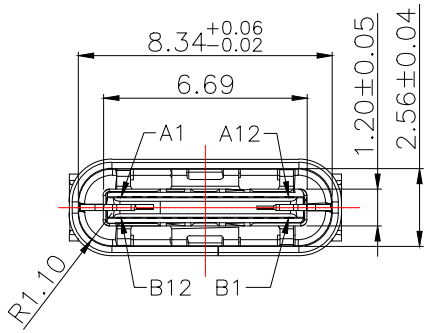










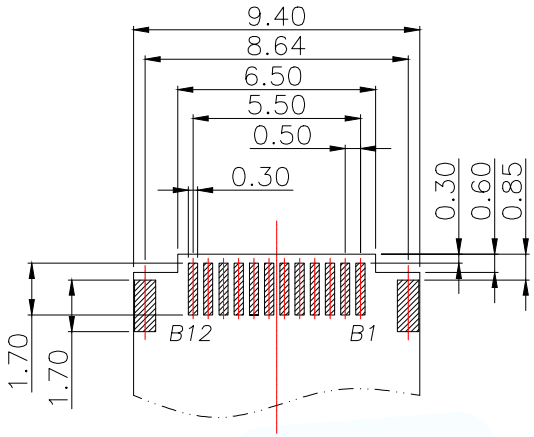


NOTE:
1.MATERIAL SPECIFICATION:
1.HOUSING:LCP,UL94 V−0.
2.CONTACTS: COPPER ALLOY(C1814)
3.MID PLATE: STAINLESS STEEL(SUS301)
4.FRONT SHELL: STAINLESS STEEL(SUS304)
5.EMI PLATE: STAINLESS STEEL(SUS301)
2.PLATING SPECIFICATION:
2−1.TERMINAL:
Ni 50u" MIN. UNDER PLATED OVER ALL.
Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
(GOLD PLATING THICKNESS FOLLOW THE P/N)
PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
2−2.FRONT SHELL:
PLATING SPECIFICATIONS FOLLOW THE P/N
2−3.EMI PLATE:
NI 50u" MIN PLATED OVER ALL
2−4.MID PLATE:
CLEAR ONLY
3.MECHANICAL PERFORMANCE,
3−1.INSERTION FORCE: 0.5~2.0kgf.
3−2.REMOVAL FORCE: 0.8kgf~2.0kgf.
3−3.DURABILITY: 10000 CYCLES.
4.ELECTRICAL PERFORMANCE,
4−1. CURRENT RATING:5.0A
VOLTAGE RATING:5.0V
4−2. LLCR:
VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
SHIELD: 50mΩ/MAX.
LLCR MAX. CHANGE OF ALL PINS: 10mΩ.
4−3.INSULATION RESISTANCE: 100MΩ MIN
4−4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
5. ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: −25°C~+85°C.
6.IR REFLOW:
THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.

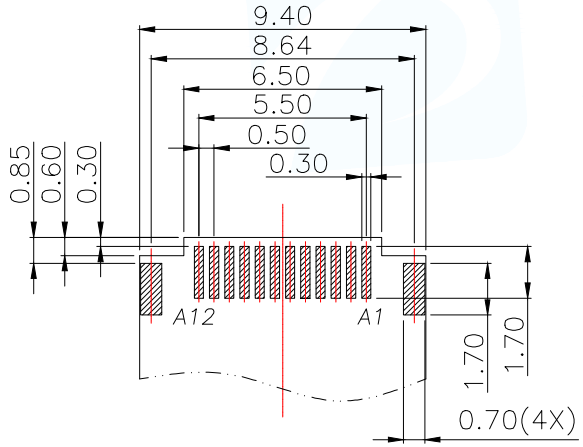
MANUFACTURE DWG	东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co,Ltd			
UNLESS OTHERWISE SPECIFED TOLERANCES		TITLE:USB C F SPLINT CONN. PCB=0.8 (L=9.30)		
		PAR	TYPEC−1102−ARP24	
DECIMALS: / ANGLES:		DWN		
X.X:±0.30 / X.°:±10°		CHKD		
X.XX:±0.20 / .X°:±8°		APVD		
X.XXX:±0.10 / .XX°:±5°	CUSTOMER COPY	SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	REV:A

ROHS Compliant

MAPX	MODIFICATION	DATE	DRAW	APPROVE

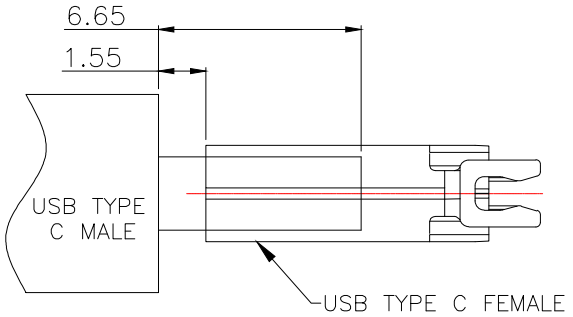


BOTTOM VIEW



RECOMMENDED PCB LAYOUT(TOP VIEW)

THICKNESS 0.8±0.05MM;DEFAULT TOLERANCE:±0.05



AFTER ASSEMBLY

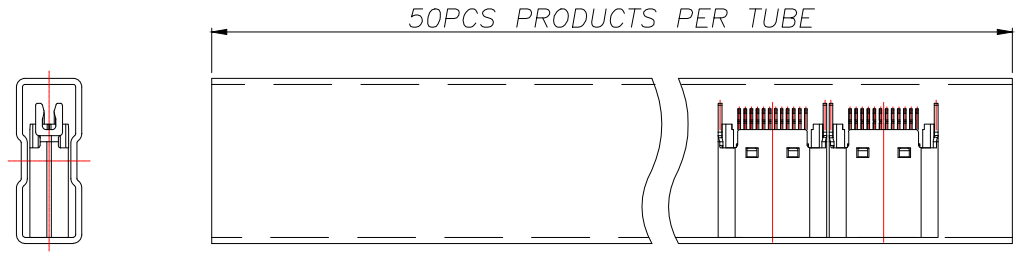
USB TYPE-C PIN ASSIGNMENTS

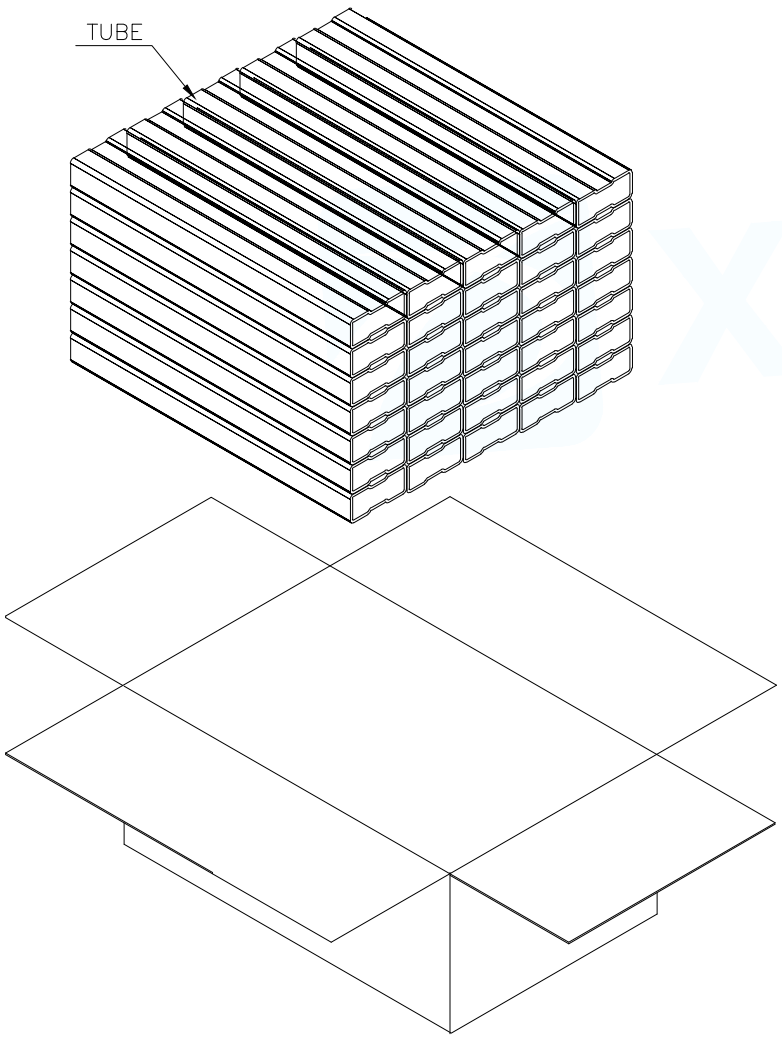
PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A2	SSTXp1	B11	SSRXp1
A3	SSTXn1	B10	SSRXn1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXn2	B3	SSTXn2
A11	SSRXp2	B2	SSTXp2
A12	GND	B1	GND

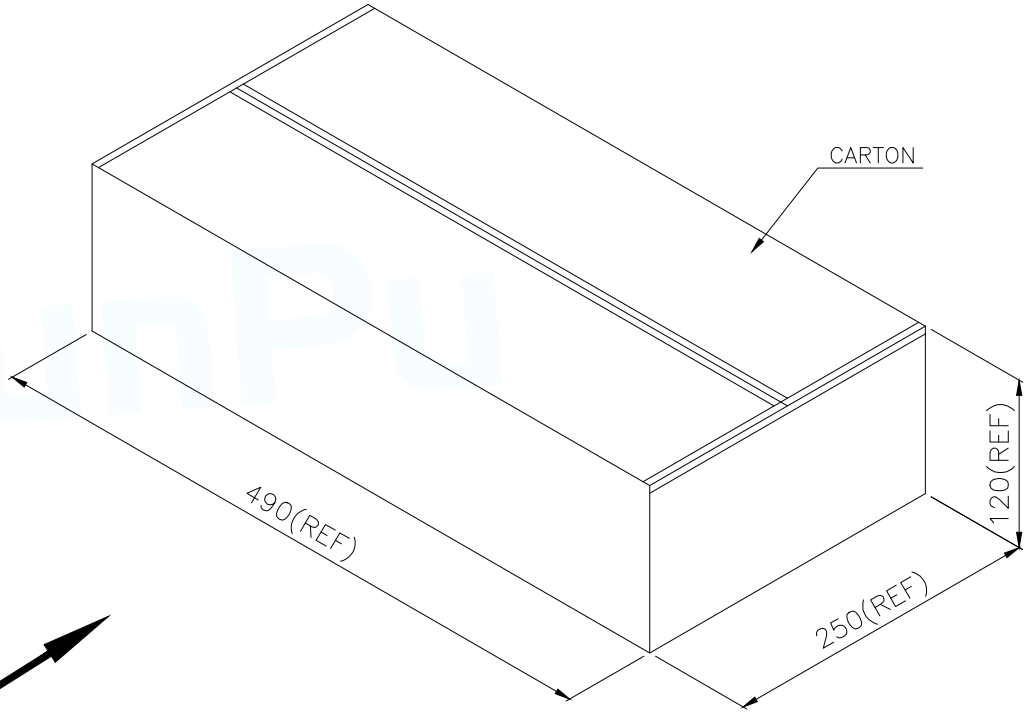
MANUFACTURE DWG	东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co,Ltd			
UNLESS OTHERWISE SPECIFED TOLERANCES		TITLE:USB C F SPLINT CONN. PCB=0.8 (L=9.30)		
		PAR	TYPEC-1102-ARP24	
DECIMALS: / ANGLES:		DWN		
X.X:±0.30 / X.°:±10°		CHKD		
X.XX:±0.20 / .X°:±8°		APVD		
X.XXX:±0.10 / .XX°:±5°		SCALE1:1	UNIT:MM	
CUSTOMER COPY		SIZE:A4	SHEET:1F1	REV:A

ROHS Compliant

MAPX	MODIFICATION	DATE	DRAW	APPROVE







MANUFACTURE DWG	东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co,Ltd			
UNLESS OTHERWISE SPECIFED TOLERANCES		TITLE:USB C F SPLINT CONN. PCB=0.8 (L=9.30)		
		PAR	TYPEC-1102-ARP24	
DECIMALS: / ANGLES:		DWN		
X.X:±0.30 / X.°:±10°		CHKD		
X.XX:±0.20 / .X°:±8°		APVD		
X.XXX:±0.10 / .XX°:±5°	CUSTOMER COPY	SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	REV:A

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FPC-1.0AX-14PWCR-H25 TYPEC-304YDSW-ACP16 WAFER-GH1.25-6PLB WAFER-VH3.96-4PLB
FPC-0.5AL-6PB FPC-0.5AX-24PWCR-H20 FPC-0.5HF-10PWBR-H20 HDMI-212L FPC-0.5FX-16PWCR-H20
FPC-0.5FX-4PWBH15 FPC-0.5FX-4PWCR-H20 MU-103-ARW64 WAFER-PH2.0-8PLB
WAFER-XH2.54-4PWZ-H62 FPC-0.5FX-20PWBH15 FPC-1.0HF-4PWAR-H20 DC-031A-A100
WAFER-PH2.0-6PWB FPC-0.5AX-30PWCR-H20 SMA-KWE-323C-H13X23-LW WAFER-PH2.0-2PJK
WAFER-WBM4.2-16PJK-GB